

# UNITED STATES PATENT AND TRADEMARK OFFICE



APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/834,297	04/12/2001	David R. Hembree	3592.5US (97-321.5)	6489	
24247	7590 11/15/2002				
TRASK BRITT			EXAM	EXAMINER	
P.O. BOX 2550 SALT LAKE CITY, UT 84110			MITCHELL	MITCHELL, JAMES M	
			ART UNIT	PAPER NUMBER	
			2827		
			DATE MAILED: 11/15/2002		

Please find below and/or attached an Office communication concerning this application or proceeding.

• .	Application No.	Applicant(s)	W	
	09/834,297	HEMBREE, DAVID	HEMBREE, DAVID R.	
Office Action Summary	Examiner	Art Unit		
	James Mitchell	2827		
The MAILING DATE of this communication ap Period for Reply	pears on the cover sheet	with the correspondence add	iress	
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1. after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a rep If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statut - Any reply received by the Office later than three months after the mailir earned patent term adjustment. See 37 CFR 1.704(b).  Status		a reply be timely filed hirty (30) days will be considered timely ONTHS from the mailing date of this co ABANDONED (35 U.S.C. 8 133).	mmunication.	
1) Responsive to communication(s) filed on <u>08/</u>	/12/2002			
	his action is non-final.			
3) Since this application is in condition for allow	vance except for formal m		e merits is	
closed in accordance with the practice under Disposition of Claims	Ex parte Quayle, 1955 (	J.D. 11, 455 O.G. 215.		
4) $\boxtimes$ Claim(s) <u>1-9</u> is/are pending in the application	ı <b>.</b>			
4a) Of the above claim(s) is/are withdra	awn from consideration.			
5) Claim(s) is/are allowed.				
6)⊠ Claim(s) <u>1-9</u> is/are rejected.				
7) Claim(s) is/are objected to.				
8) Claim(s) are subject to restriction and/o	or election requirement.			
Application Papers				
9) The specification is objected to by the Examine				
10) The drawing(s) filed on is/are: a) acce				
Applicant may not request that any objection to the				
11) The proposed drawing correction filed on		disapproved by the Examine	er.	
If approved, corrected drawings are required in re				
12) The oath or declaration is objected to by the E.	xammer.			
Priority under 35 U.S.C. §§ 119 and 120	nn mriarity under 25 H C C	\$ \$ 110(a) (d) ar (f)		
13) Acknowledgment is made of a claim for foreig	in priority under 35 0.5.C	. 9 119(a)-(d) or (i).		
a) All b) Some * c) None of:	ata haya haan raasiyad			
1. Certified copies of the priority documen		Application No.		
<ul><li>2. Certified copies of the priority documen</li><li>3. Copies of the certified copies of the priority</li></ul>			Stage	
<ul> <li>3. Copies of the certified copies of the price application from the International Between the attached detailed Office action for a list.</li> </ul>	ureau (PCT Rule 17.2(a)	).	Stage	
14) Acknowledgment is made of a claim for domes	tic priority under 35 U.S.	C. § 119(e) (to a provisional	application).	
<ul> <li>a) ☐ The translation of the foreign language pr</li> <li>15)☐ Acknowledgment is made of a claim for domes</li> </ul>				
Attachment(s)	· •	- 7		
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449) Paper No(s)	5) Notice	ew Summary (PTO-413) Paper No( of Informal Patent Application (PTO		

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#### **DETAILED ACTION**

1. This office action is in response to the amendment filed February 8, 2002.

## Claim Rejections - 35 USC § 103

- 2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 3. Claims 1 and 6 are rejected under 35 U.S.C. 103(a) as being unpatentable over Schneider et al (U.S 5,610,442) in combination with MacDonald Jr., et al. (U.S 5,905,638).
- 4. Schneider discloses a semiconductor assembly comprising a substrate (36) and a die (306) having a plurality of edges, and having a back side adhesively attached to a substrate (102), a plurality of bond pads on a first portion of the active surface of said die adjacent two edges (via sidewall edges), and an encapsulant (404a) covering a portion of said substrate, die and bond pads excluding a heat sink (54) with fins inherently attached to an adhesive on a second portion of the active surface.
- 5. Schnieder does not appear to disclose a gel elastomer contacting a portion of the active surface or the heat sink being attached to the gel elastomer, however MacDonald (Fig 1) utilizes a gel elastomer (22) contacting a portion of the active surface (18) with a heat sink (25) attached to the gel elastomer.
- 6. It would have been obvious to one of ordinary skill in the art to incorporate an elastomer material between the heat sink and chip of Schneider in order to enhance

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thermal conduction and to provide shock protection of the device as taught by MacDonald (Columns 5-6, Lines 65-6).

- 7. Claims 3-5, 8 and 9 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chiu et al. (U.S 6,121,680) in combination with MacDonald.
- 8. Chiu (Fig 1) discloses a substrate (16) with an inherent plurality of circuits on a portion thereof, a die (14) having a plurality of bond pads (inherent with the contact of solder balls on the surface of a chip) located on the active surface thereof, and having a backside surface, a plurality of solder balls (not labeled, but alternatively shown as 116) connecting a portion of the plurality of pads of the die to at least a portion of the plurality of inherent circuits on the substrate, a heat sink cap with fins (12) covering an inherent compliant adhesive elastomer (18), the die, solder balls and a portion of the substrate.
- 9. Chiu does not explicitly state that the elastomer is a gel filled with thermally conductive material, however MacDonald utilizes a gel silicone elastomer (silicone elastomer is chemically bonded and therefore inherently cross linked) filled with a thermally conductive material (Column 5, Lines 12-18).
- 10. It would have been obvious to one of ordinary skill in the art to form the assembly of Chiu with a cross linked gel silicone elastomer filled with thermally conductive material between the chip and heat sink, in order to enhance thermal conduction as taught by MacDonlad (Column 6, Lines 2-3).

## Response to Arguments

11. Applicant's arguments with respect to claims 1-9 have been considered but are most in view of the new ground(s) of rejection.

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#### Conclusion

12. Any inquiry concerning this communication or earlier communications from the examiner should be directed to James Mitchell whose telephone number is (703) 305-0244. The examiner can normally be reached on M-F 10:30-8:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, David L. Talbott can be reached on (703) 305-9883. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 305-3432 for regular communications and (703) 305-3230 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

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November 14, 2002

VID E. GRAYBILL MARY EXAMINE